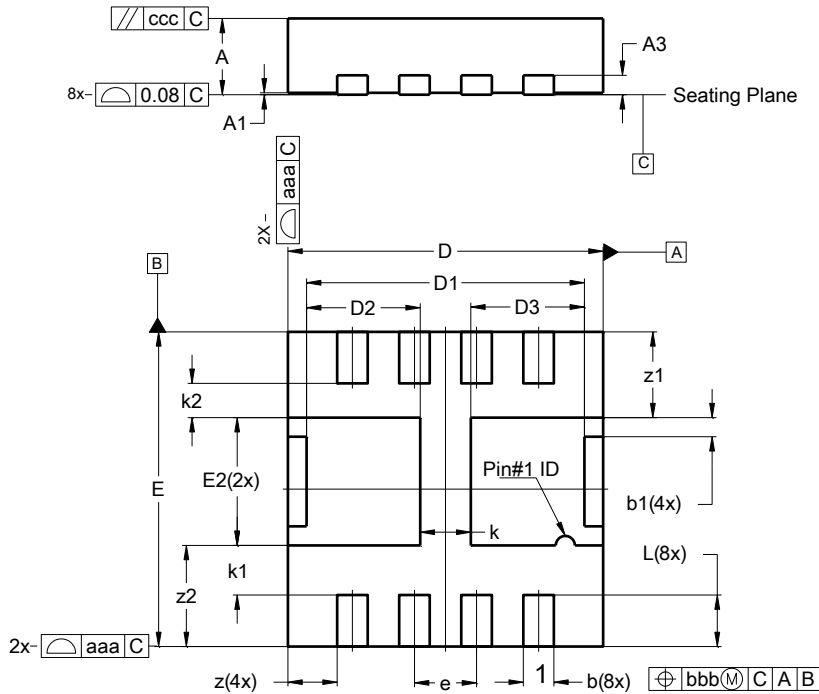


Package Outline Dimensions

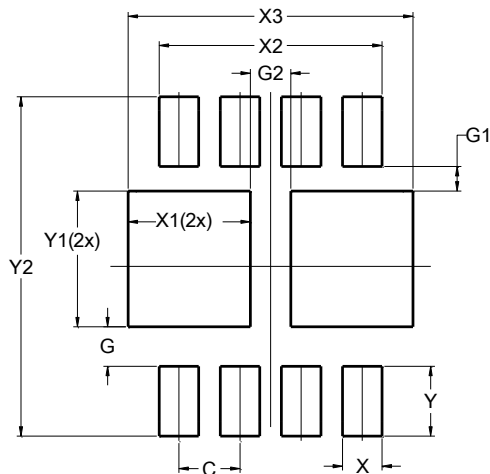
PowerDI3333-8 (Type G)



PowerDI3333-8 (Type G)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	--	--	0.203
b	0.27	0.37	0.32
b1	0.15	0.25	0.20
D	3.25	3.35	3.30
D1	2.81	3.01	2.91
D2	1.09	1.29	1.19
D3	1.09	1.29	1.19
E	3.25	3.35	3.30
E2	1.24	1.44	1.34
e	0.65BSC		
L	0.49	0.59	0.54
k	--	--	0.53
k1	--	--	0.52
k2	--	--	0.36
z	--	--	0.515
z1	--	--	0.90
z2	--	--	1.06
aaa	0.25		
bbb	0.10		
ccc	0.10		
All Dimensions in mm			

Suggested Pad Layout

PowerDI3333-8 (Type G)



Dimensions	Value (in mm)
C	0.650
G	0.420
G1	0.260
G2	0.430
X	0.420
X1	1.300
X2	2.370
X3	3.030
Y	0.740
Y1	1.440
Y2	3.600

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.